Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. - 35. (Canceled)

36. (Currently Amended) A substrate treating apparatus for performing a series of substrate treating processes to form a pattern on a substrate by forming a coating film on the substrate, exposing the substrate having the coating film formed thereon, and developing the exposed substrate, said apparatus comprising;

type selecting means for selecting at least one type from different types of substrate treating conditions;

substrate treating condition selecting means for selecting one substrate treating condition from a plurality of substrate treating conditions of the same type selected by said type selecting means; ~~and~~

correlation storage means for storing correlations between plurality of substrate treating conditions, a pivotal shift which is a difference between an actual pattern size and a mask pattern size, said actual pattern size being obtained from a processing carried out at a pivotal point which is an exposing condition resulting in little variation in pattern size even with variations in focus of exposing light, a substrate treating condition relating to acid diffusion that influences spread of an acid produced in said coating film by exposure of said coating film, and a substrate treating condition relating to dissolving rate that influences a dissolving rate of said coating film by development; and

developing time derivation means for deriving a developing time for developing the exposed substrate based on the at least one type, the one substrate treating condition, and the stored correlations;

wherein said series of substrate treating processes is performed based on said substrate treating condition selected by said substrate treating condition selecting means and said correlations read from said correlation storage means.

37. (Original) A substrate treating apparatus as defined in claim 36, wherein said type relates to a coating solution for forming said coating film on the substrate.

38. (Original) A substrate treating apparatus as defined in claim 36, wherein said type relates to pattern size.

39. (Original) A substrate treating apparatus as defined in claim 36, wherein said type relates to pattern form.

40. (Original) A substrate treating apparatus as defined in claim 36, wherein, after performing said series of substrate treating processes based on said correlation read from said correlation storage means, results of the processes are stored in said correlation storage means, to reflect said results of the processes on a next series of substrate treating processes.

41. - 45. (Canceled)

46. (Currently Amended) A substrate treating apparatus for performing a series of substrate treating processes to form a pattern on a substrate by forming a coating film on the substrate, exposing the substrate having the coating film formed thereon, and developing the exposed substrate, said apparatus comprising:

switching means for selecting whether to set a substrate treating condition according to a pivotal shift which is a difference between an actual pattern size and a mask pattern size, said actual pattern size being obtained from a processing carried out at a pivotal point which is an exposing condition resulting in little variation in pattern size even with variations in focus of exposing light;

type selecting means for selecting at least one type from different types of substrate treating conditions;

substrate treating condition selecting means for selecting one substrate treating condition from a plurality of substrate treating conditions of the same type selected by said type selecting means; ~~and~~

correlation storage means for storing correlations between a plurality of substrate treating conditions, said pivotal shift, a substrate treating condition relating to acid diffusion that

influences spread of an acid produced in said coating film by exposure of said coating film, and a substrate treating condition relating to dissolving rate that influences a dissolving rate of said coating film by development; and

developing time derivation means for deriving a developing time for developing the exposed substrate based on the at least one type, the one substrate treating condition, and the stored correlations;

wherein said series of substrate treating processes is performed based on said substrate treating condition selected or a substrate treating condition deselected by said switching means; and

wherein, when the substrate treating conditions are switched by said switching means, said series of substrate treating processes is performed based on said substrate treating condition selected by said substrate treating condition selecting means and said correlations read from said correlation storage means.

47. (Original) A substrate treating apparatus as defined in claim 46, wherein said type relates to a coating solution for forming said coating film on the substrate.

48. (Original) A substrate treating apparatus as defined in claim 46, wherein said type relates to pattern size.

49. (Original) A substrate treating apparatus as defined in claim 46, wherein said type relates to pattern form.

50. (Original) A substrate treating apparatus as defined in claim 46, wherein, after performing said series of substrate treating processes based on said correlations read from said correlation storage means, results of the processes are stored in said correlation storage means, to reflect said results of the processes on a next series of substrate treating processes.